

Oral - Wed., Jan. 15

CONFERENCE SCIENTIFIC PROGRAM

Tuesday, January 14

19:00 - 21:00 **Reception**

Wednesday, January 15

09:00 - 09:15 **Introductory** (Symposion : Room A)

Session I : Plenary Talks (Symposion : Room A)

09:15 - 09:50 **Challenges of High Germanium Content SiGe Structures**
Plenary - Erich Kasper (University of Stuttgart)

09:50 - 10:25 **The Revolution in SiGe: Impact on Device Electronics**
Plenary - David Hareme (IBM)

10:25 - 10:45 **Break**

Session II : Invited Talks (1) (Symposion : Room A)

10:45 - 11:10 **Circuit Applications of High-Performance SiGe:C HBTs Integrated in BiCMOS Technology**
Invited - W. Winkler, J. Borngräber, B. Heinemann, H. Rücker, R. Barth, J. Bauer, D. Bolze, E. Bugiel, J. Drews, K.-E. Ehwald, T. Grabolla, U. Haak, W. Höppner, D. Knoll, D. Krüger, B. Kuck, R. Kurps, M. Marschmeyer, H. H. Richter, P. Schley, D. Schmidt, R. Scholz, B. Tillack, D. Wolansky, H.-E. Wulf, Y. Yamamoto and P. Zaumseil (IHP)

11:10 - 11:35 **Advanced SiGe HBT Technologies and Applications**
Invited - Katsuyoshi Washio (Hitachi, Ltd.)

11:35 - 12:00 **Strained Si MOSFETs on Bulk and SiGe-on-Insulator (SGOI) Substrates**
Invited - K. Rim, L. Shi, K. Chan, J. Chu, D. Boyd, K. Jenkins, J. Ott, D. Lacey, P. Mooney, M. Cobb, N. Klymko, F. Jamin, S. Koester, and T. Kanarsky (IBM)

12:00 - 12:25 **Microwave performances of silicon heterostructure-FETs**
Invited - F. Aniel¹, M. Enciso¹, P. Crozat¹, R. Adde¹, T. Hackbarth², J.-H. Herzog², U. König²
(¹)Paris-South University, (²)DaimlerChrysler Research Center)

12:25 - 13:45 **Lunch**

[**Parallel Session**]

Session III-A : MOSFET (Symposion : Room A)

13:45 - 14:00 **25nm Gate Length Strained Silicon CMOS** - Qi Xiang, Jung-Suk Goo, Haihong Wang, Yayoi Takamura, Bin Yu, James Pan, Ammar Nayfeh, Allison Holbrook, Farzad Arasnia, Eric Paton, Paul Besser, Max Sidorov, Ercan Adem, Anthony Lochtefeld*, Glyn Braithwaite*, Matthew Currie*, Richard Hammond*, Mayank Bulsara*, Ming-Ren Lin (Advanced Micro Devices, Inc., *AmberWave Systems Corporation)

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- 14:00 - 14:15 **Performance Enhancement in 70nm Channel Length Strained Si_{0.9}Ge_{0.1} pMOSFETs** - Regular
Zhonghai Shi, David Onsongo, Raghaw Rai*, Srikanth B. Samavedam* and Sanjay K. Banerjee (The University of Texas at Austin, *Motorola (Digital DNA Laboratories, Dan Noble Center))
- 14:15 - 14:30 **Fabrication of 0.12- μ m SiGe-Channel MOSFET Containing High Ge Fraction with Ultrashallow Source/Drain Formed by Selective B-Doped SiGe CVD** - Regular
Doohwan Lee, Shinobu Takehiro, Masao Sakuraba, Junichi Murota and Toshiaki Tsuchiya* (Tohoku University, *Shimane University)
- 14:30 - 14:45 **Fabrication of strained Ge channel p-MOSFET with extremely high mobility** - Regular
T. Irisawa, S. Koh, K. Nakagawa*, Y. Shiraki (The University of Tokyo, *Yamanashi University)
- 14:45 - 15:00 **Strained-SiGe Channel p-MOSFETs with Platinum-Germanosilicide Schottky Source/Drain** - Regular
Keiji Ikeda, Yoshimi Yamashita, Akira Endoh, Tetsu Fukano, Kohki Hikosaka, and Takashi Mimura (Fujitsu Laboratories)
- 15:00 - 15:15 **SiGe Elevated Source/Drain Structure and Nickel Silicide Contact Layer for sub 0.1 μ m MOSFET** - Regular
JeoungChill Shim, HyuckJae Oh, Hoon Choi, Takeshi Sakaguchi, Hiroyuki Kurino and Mitsumasa Koyanagi (Tohoku University)
- 15:15 - 15:30 **Low frequency noise suppression and DC characteristics enhancement in sub- μ m metamorphic p-MOSFETs with strained Si_{0.3}Ge_{0.7} channel grown by MBE** - Regular
M. Myronov, S. Durov, O.A. Mironov, E.H.C. Parker and T.E. Whall, T. Hackbarth*, G. Hock*, H.J. Herzog* and U. Konig* (University of Warwick, *DaimlerChrysler Research Center)
- 15:30 - 15:50 **Break**

Session IV-A : MOSFET (Symposion : Room A)

- 15:50 - 16:05 **Low-Frequency Noise Characteristics in Strained SiGe Channel pMOSFET** - Regular
Akira Asai, Junko Sato-Iwanaga, Akira Inoue, Yoshihiro Hara, Yoshihiko Kanzawa, Haruyuki Sorada, Takahiro Kawashima, Teruhito Ohnishi, Takeshi Takagi, and Minoru Kubo (Matsushita Electric Industrial Co., Ltd.)
- 16:05 - 16:09 **High Performance Si/SiGe Heterostructure MOSFETs for Low power and Low Noise RF/Microwave Circuit Applications** - Short
P. W. Li, W. M. Liao, C. C. Shih, T. S. Kuo, L. S. Lai*, Y. T. Tseng*, and M. J. Tsai* (National Central University, *ITRI)
- 16:09 - 16:13 **A Proposal of Multi-Layer Channel MOSFET: The Application of Selective Etching for Si/SiGe Stacked Layers** - Short
T. Sakai, S. Ohmi, D. Sasaki, M. Sakuraba* and J. Murota* (Tokyo Institute of Technology, *Tohoku University)
- 16:13 - 16:17 **Low Frequency Noise and Hetero-Interface Traps in SiGe-Channel pMOSFETs** - Short
Toshiaki Tsuchiya, Yuji Imada, and Junichi Murota* (Shimane University, *Tohoku University)
- 16:17 - 16:21 **Investigation of the Leakage Current in Si_{0.7}Ge_{0.3} pMOSFETs Fabricated by Selective Epitaxial Growth** - Short
A. Inoue, H. Sorada, Y. Hara, K. Nozawa, A. Asai Y. Kanzawa and T. Takagi (Matsushita Electric Industrial Co., Ltd.)
- 16:21 - 16:25 **Influence of roughness with long correlation length on the electron mobility of strained silicon devices** - Short
Isao Kitagawa, Takuya Maruizumi, and Nobuyuki Sugii (Hitachi)

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- 16:25 - 16:29 **Electrical properties of Si_{1-y}C_y/Si/SiO₂ stacks for sub 50nm strained-channel**
Short **nMOSFETs** - [1,2]F. Ducroquet, [1]T. Ernst, [1,2]O. Weber, [1]J.-M. Hartmann, [1]V. Loup, [3]P. Besson, [1]L. Brévard, [1]J.L. Di Maria, [1]S. Deleonibus ([1]CEA – LETI/DTS – CEA/GRE, [2]LPM, INSA-Lyon, [3]STMicroelectronics)
- 16:29 - 16:33 **Analysis of carrier generation lifetime in strained-Si / SiGe heterojunction MOSFETs from capacitance transient** - L.K.Bera, Shajan Mathew, N.Balasubramanian, G. Braithwaite*, M.T. Currie*, F. Singaporewala*, J. Yap*, R. Hammond*, A. Lochtefeld*, M. T. Bulsara*, and E. A. Fitzgerald* (Institute of Microelectronics, *AmberWave Systems Corp.)
- 16:33 - 16:37 **Minority Carrier Lifetime and Diffusion Length in Si_{1-x-y}Ge_xC_y and Si_{1-y}C_y Heterolayers** - S. K. Samanta, G. K. Dalapati, S. Chatterjee and C. K. Maiti (IIT)
- 16:37 - 16:41 **Electrical Properties of ZrO₂ Films on Si_{1-x-y}Ge_xC_y Epitaxial Layers** - S. Chatterjee, G. K. Dalapati, S. K. Samanta, and C. K. Maiti (IIT)
- 16:41 - 16:45 **Low-voltage CMOS operation of SiGe Heterostructure DTMOS** - H. Sorada, A. Inoue, Late News Y. Hara, K. Nozawa, A. Asai, T. Kawashima, K. Katayama, and T. Takagi (Matsushita Electric Industrial Co., Ltd)
- 16:45 - 17:20 **Break [Next : Poster Session (1)]**

[Parallel Session]

Session III-B : HBT and The Other Devices (Symposion : Room B)

- 13:45 - 14:00 **Avalanche Considerations in SiGe HBT Scaling** - Greg Freeman, Basanth Jagannathan, Regular Jae-Sung Rieh (IBM Microelectronics)
- 14:00 - 14:15 **Emitter Resistance Improvement in High-Performance SiGe HBTs** - Alvin Joseph, Regular Peter Geiss, Xuefeng Liu, Jeffrey Johnson, Kathy Schonenberg*, Ashima Chakravarti*, David Ahlgren*, and James Dunn (IBM)
- 14:15 - 14:30 **Self-Aligned Heavily-Boron-Doped SEG SiGe HBT** - Eiji Ohue[1], Yukihiro Kiyota[1], Regular Takashi Hashimoto[1], Tsutomu Udo[2], Akihiro Kodama[3], Hiromi Shimamoto[3], Reiko Hayami[1] and Katsuyoshi Washio[1] ([1]Hitachi Ltd., [2]Hitachi ULSI Systems Co. Ltd., [3]Hitachi Device Engineering Co. Ltd.)
- 14:30 - 14:45 **Influence of the Extrinsic Base on the Base Current Kink in SiGe BJTs** - Alexei Regular Sadovnikov, Tracey Krakowski, and Monir El-Diwany (National Semiconductor Corp.)
- 14:45 - 15:00 **Design and optimization of a 200 GHz SiGe HBT collector profile by TCAD.** - Regular Andreas D. Stricker, Jeffrey B. Johnson, Greg Freeman, and Jae-Sung Rieh (IBM Microelectronics Division)
- 15:00 - 15:15 **Resonant tunneling in Si-SiGe superlattices on relaxed buffer substrates** - S. Tsujino, Regular S. Mentese, L. Diehl, E. Muller, B. Haas, D. Bachli, S. Stutz, H. Sigg, D. Grutzmacher, J. Faist* (Paul Scherrer Institut, *University of Neuchatel)
- 15:15 - 15:50 **Break**

Session IV-B : HBT and The Other Devices (Symposion : Room B)

- 15:50 - 15:54 **The Effect of C on Emitter-Base Design for a Single-Polysilicon SiGe:C HBT with an IDP Emitter** - Erik Haralson, Erdal Suvar, Gunnar Malm, Henry Radamson, Yong-Bin Wang, Mikael Östling (Royal Institute of Technology (KTH))

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- 15:54 - 15:58 **Characterization of leakage current for SiGeC heterojunction bipolar transistors with a selectively grown collector** - E. Suvar, E. Haralson, H. H. Radamson, Y.-B. Wang, B. G. Malm and M. Östling (Royal Institute of Technology (KTH))
Short
- 15:58 - 16:02 **ESD Characterization of SiGe HBT in 0.18- μm SiGe BiCMOS Process** - Shiao-Shien Chen, Tung-Yang Chen, Tien-Hao Tang, Shao-Chang Huang, Tsun-Lai Hsu, Hua-Chou Tseng, Jen-Kon Chen, and Chiu-Hsiang Chou* (United Microelectronics Corporation, *Providence University)
Short
- 16:02 - 16:06 **The optimal base design for SiGe heterojunction bipolar transistors with high f_T** - L.S. Lai, Y.H. Liu, C.S. Liang, Y.T. Tseng, Y.M. Shiu, P.S. Chen, S.C. Lu, C.W. Liu and M.-J. Tsai (ITRI)
Short
- 16:06 - 16:10 **Low frequency noise behavior of advanced SiGe HBT** - A.Rennane*, L.Bary*, G. Niu**, J.D. Cressler**, J. Joseph***, J.Graffeuil* and R. Plana* (*LAAS-CNRS, **Alabama Microelectronics Science and Technology Center, ***IBM Microelectronics)
Short
- 16:10 - 16:14 **Reliability properties of SiGe HBT** - A.Rennane*, L.Bary*, J.L.Roux **, J.Kuchenbecker **, J.Graffeuil* and R. Plana* (*LAAS-CNRS and Université Paul Sabatier, ** CNES)
Short
- 16:14 - 16:18 **Achieving a SiGe HBT Epitaxial Emitter with Novel LowThermal Budget Technique** - Paul Brabant, Jianqing Wen, Joe Italiano, Trevan Landin, Nyles Cody and Lee Haen (ASM America Inc.)
Short
- 16:18 - 16:22 **Evaluation of Compact Noise Modeling for Si/SiGe HBTs Based on Hierarchical Hydrodynamic Noise Simulation** - M. Bartels , B. Neinhüs , C. Jungemann , B. Meinerzhagen (Universität Bremen)
Short
- 16:22 - 16:26 **Comparison of State-of-the-Art Bipolar Compact Models for SiGe-HBTs** - A. Chakravorty, R. Garg, and C. K. Maiti (IIT)
Short
- 16:26 - 16:30 **A noise and power analysis of SiGe HBT's for RF applications** - J. Raoult*, J. Verdier*, F. Calmon*, P.J. Viverge**, C. Gontrand* (*Laboratoire de Physique de la Matière, **Centre de Génie Electrique de Lyon)
Short
- 16:30 - 16:34 **A Direct Extraction Feature for Scattering Parameters of SiGe-HBTs** - S. Wagner[1], V. Palankovski[1], T. Grasser[1], G. Röhrer[2], and S. Selberherr[1] ([1]TU Vienna, [2]AustriamicrosystemsAG)
Short
- 16:34 - 16:38 **60nm gate-length Si/SiGe HEMT** - A. Kasamatsu*, K. Kasai*, K. Hikosaka*, T. Matsui* and T. Mimura** (*Communications Research Laboratory, **Fujitsu Laboratories Ltd.)
Short
- 16:38 - 16:42 **SiGe virtual substrate HMOS transistor for analogue applications** - K. Michelakis, S. Despotopoulos, V. Gaspari, A. Vilches, K. Fobelets, C. Papavassiliou, C. Toumazou, J. Zhang (Imperial College)
Short
- 16:42 - 16:46 **Effect of temperature on the transfer characteristic of a 0.5 μm -gate Si:SiGe depletion-mode n-MODFET** - V. Gaspari†, K. Fobelets, J.E. Velazquez-Perez*, R. Ferguson, K. Michelakis, S.Despotopoulos, and C. Papavassilliou (Imperial College London, *Universidad de Salamanca)
Short
- 16:46 - 16:50 **Influence of substrate thinning on the threshold voltage of Si:SiGe Heterojunction MOSFETs** - S.M. Li, K. Fobelets , J.E. Velazquez-Perez*, V. Gaspari, R. Ferguson, K. Michelakis, S. Despotopoulos, and C. Papavassilliou (Imperial College London, *Universidad de Salamanca)
Short
- 16:50 - 16:54 **Nonvolatile Memory based on Ge/Si Hetero-Nanocrystals** - H.G. Yang, Y. Shi, L. Pu, R. Zhang, B. Shen, P. Han, S.L. Gu, and Y.D. Zheng (Nanjing University)
Short

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16:54 - 16:58 **Si/SiGe heterojunction collector for low loss operation of Trench IGBT** - Tsugutomo Short
Kudoh and Tanemasa Asano (Kyushu Institute of Technology)

16:58 - 17:20 **Break [Next : Poster Session (1)]**

[**End of Parallel Session**]

17:20 - 18:40 **Session V : Poster Session (1)** (Symposion : Room C)
(see the page "xvi")

18:40 - 19:00 **Break**

19:00 - 21:00 **Banquet**

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Session VI : Invited Talks (2) (Symposion : Room A)

08:45 - 09:10 **High Performance RF Front End Circuits using SiGe:C BiCMOS + Copper Technologies**
Invited
- Glenn Watanabe, Jeff Ortiz, Rick Holbrook (Motorola)

09:10 - 09:35 **Numerical Simulation of Strained Si/SiGe Devices: The Hierarchical Approach**
Invited
- B. Meinerzhagen, C. Jungemann, B. Neinhüs, M. Bartels (Universität Bremen)

09:35 - 10:00 **Selective Epitaxial Growth of SiGe:C for High Speed HBTs**
Invited
- H. Schäfer, J. Böck, R. Stengl, H. Knapp, K. Aufinger, M. Wurzer, S. Boguth, M. Rest, R. Schreiter, and T.F. Meister (Infineon Technologies)

10:00 - 10:20 **Break**

Session VII : Invited Talks (3) (Symposion : Room A)

10:20 - 10:45 **Interfacial Reaction and Electrical Properties in Ni/Si and Ni/SiGe Contacts**
Invited
- S. Zaima¹, O. Nakatsuka¹, A. Sakai¹, J. Murota², and Y. Yasuda¹ (¹Nagoya University, ²Tohoku University)

10:45 - 11:10 **Avoiding loading effects and facet growth: key parameters to successful implementation of selective epitaxial SiGe deposition for HBT-BiCMOS and high-mobility hetero-channel pMOS devices**
Invited
- Roger Loo, and Matty Caymax (IMEC)

11:10 - 11:35 **Laterally controlled nucleation of Ge nano dots by in-situ focused ion beam surface modification**
Invited
- M. Kammner*, R. Hull*, and F.M. Ross+ (*University of Virginia, +IBM T.J. Watson Research Center)

11:35 - 12:00 **Self assembled SiGe islands: 2µm photoluminescence emission and 3D composition profiles**
Invited
- U. Denker(a), M. Stoffel(a), H. Sigg(b), O. G. Schmidt(a) ((a) Max-Planck-Institute, (b) Paul Scherrer Institut)

12:00 - 13:20 **Lunch**

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[Parallel Session]

Session VIII-A : Strain Control , Epitaxy and Impurity (Symposion : Room A)

- 13:20 - 13:35 **Development of a new type of SiGe thin strain relaxed buffer based on the incorporation of a carbon-containing layer** - Romain Delhougne, Philippe Meunier-Beillard*, Matty Caymax, Roger Loo, Wilfried Vandervorst (IMEC, *Philips Research Leuven)
- 13:35 - 13:50 **Thin strain relaxed SiGe buffer layers on Si and SOI wafers made by He⁺ ion implantation and annealing** - S. Mantl[1], B. Holländer[1], N. Hüging[2], M. Luysberg[2], St. Lenk[1], S.M. Hoog[1], H.-J. Herzog[3], T. Hackbarth[3], R. Loo[4], M. Bauer[5] ([1-2]Research Centre Juelich, [3]DaimlerChrysler, [4]IMEC, [5]ASM Germany)
- 13:50 - 14:05 **Low temperature H₂ cleaning of Si surface for 0.18-um SiGe-BiCMOS base epitaxy** - T.Tominari, Y.Nonaka, K.Sakai, S.Wada, T.Saito, K.Tokunaga, T.Jimbo, T.Udo*, Y.Kiyota and T.Hashimoto (Hitachi,Ltd., *Hitachi ULSI Systems)
- 14:05 - 14:20 **N₂ as carrier gas: an alternative to H₂ for enhanced epitaxy of Si, SiGe and SiGe:C** - P. Meunier-Beillard*, M. Caymax**, K. Van Nieuwenhuysen**, G. Doumen**, B. Brijs**, M. Hopstaken†, L. Geenen** and W. Vandervorst** (*Philips Research Leuven, **IMEC, †Philips Research Laboratories)
- 14:20 - 14:35 **Selective Epitaxial Growth of Si and SiGe for MOS transistors** - J.-M. Hartmann, F. Bertin, G. Rolland, F. Laugier, M.N. Séméria, P. Besson and P. Gentile (CEA-DRT – LETI/DTS – CEA/GRE.)
- 14:35 - 14:50 **High Performance SiGe:C HBTs Using Atomic Layer Base Doping** - Bernd Tillack, Yuji Yamamoto, Dieter Knoll, Bernd Heinemann, Peter Schley, Biswanath Senapati and Dietmar Krüger (IHP)
- 14:50 - 15:05 **Enhanced intrinsic Arsenic diffusion in SiGe strained layers.** - A. Pakfar, P. Holliger*, C. Fellous, D. Dutartre. T. Schwartzmann and H. Jaouen. (STMICROELECTRONICS, *CEA-Leti)
- 15:05 - 15:20 **On the mechanism of ion- implanted As diffusion in relaxed SiGe** - S. Eguchi, S. J. Rhee[1], D.L. Kwong[1], I. Åberg[2], and J.L. Hoyt [2] (Hitachi Ltd., [1]Univ. of Texas at Austin, [2]MIT)
- 15:20 - 15:40 **Break**

Session IX-A : Strain Control , Epitaxy and Impurity (Symposion : Room A)

- 15:40 - 15:44 **Fabrication SiGe-on-insulator by rapid thermal annealing of Ge thin film on Si-on-insulator substrate** - K.Kutsukake, N.Usami, K.Fujiwara, T.Ujihara, G.Sazaki, B.P.Zhang*and K.Nakajima (Tohoku University, *The Institute of Physical and Chemical Research (RIKEN))
- 15:44 - 15:48 **Formation of thin SiGe virtual substrates by ion implantation into Si substrates** - K. Sawano^a, Y. Hirose^b, S. Koh^a, K. Nakagawa^c, T. Hattori^b, and Y. Shiraki^a ((a) The University of Tokyo, (b) Musashi Institute of Technology, (c) Yamanashi University)
- 15:48 - 15:52 **Strain-relaxation mechanisms of SiGe layers formed by two-step growth on Si(001) substrates** - T. Egawa, T. Yamamoto, N. Taoka, O. Nakatsuka, A. Sakai, S. Zaima, and Y. Yasuda (Nagoya University)
- 15:52 - 15:56 **Dislocation structures and strain-relaxation in SiGe buffer layers on Si (001) with thin Ge interlayer** - T. Yamamoto, T. Egawa, N. Taoka O. Nakatsuka, A. Sakai, S. Zaima and Y. Yasuda (Nagoya University)

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- 15:56 - 16:00 **Evaluation of relaxation of strained-Si layers on SiGe-On-Insulator (SGOI) structures after mesa isolation** - Koji Usuda, T.Mizuno, T.Tezuka, N.Sugiyama, Y.Moriyama, S.Nakaharai and S.Takagi (MIRAI Project, ASET)
Short
- 16:00 - 16:04 **Influence of SiGe interlayer on the initial growth of $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ on Si(100)** - S. Ariyoshi, S. Takeuchi, O. Nakatsuka,* A. Sakai, S. Zaima,** and Y. Yasuda (Nagoya University)
Short
- 16:04 - 16:08 **Roughening mechanisms of tensily strained $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ films grown by UHV-CVD : a way to maximize substitutional C incorporation** - Cyril Calmes[1], Daniel Bouchier[1], Catherine Clerc[2], Yulin Zheng[3] ([1-2]Université Paris-Sud, [3]Université Paris VI et Paris VII)
Short
- 16:08 - 16:12 **Production-ready Dry Cleaning and Deposition Processes for Low-Temperature Si and SiGe Epitaxy** - Kummer, M. [a], Dommann, A.[a], Buschbaum T. [b], Buschbeck, H. M.[b], Erhart, A.[b], Goeggel, Y.[b], Rosenblad, C. [b], Wiltsche, S.[b], Ramm, J.[b] ((a) Interstate University of Applied Science, (b) Unaxis Semiconductors)
Short
- 16:12 - 16:16 **$\text{Si}_{1-x}\text{Ge}_x/\text{Si}$ strained epitaxial layer grown by UV/UHV/CVD** - Huiyong Hu, Heming Zhang, Xianying Dai, *Kaicheng Li, Bin Shu, Yi Lv (Xidian University, *National Lab of Analog Ics)
Short
- 16:16 - 16:20 **Si/SiGe Selective Epitaxial Growth by a Single-wafer Cold-wall UHVCVD System** - Supika Mashiro, Hiroki Date, Junko Nakatsuru, Satoshi Hitomi, and Junro Sakai (Anelva Corporation)
Short
- 16:20 - 16:24 **Carbon incorporation study for SiGeC epitaxy optimization in RTCVD** - F. Deleglise, C. Fellous and D. Dutartre (STMICROELECTRONICS)
Short
- 16:24 - 16:28 **Low Temperature, High Growth Rate Epitaxial Silicon and Silicon Germanium Alloy Films** - Michael A. Todd and K. Doran Weeks (ASM America)
Short
- 16:28 - 16:32 **Growth of high quality epitaxial $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ layers using chemical vapor deposition** - J. Hallstedt, E. Suvar, P. O. A. Persson*, L.Hultman* and H. H. Radamson (Royal Institute of Technology (KTH), *Linköping University)
Short
- 16:32 - 16:36 **Reduced Pressure Chemical Vapour Deposition of high C content Si / $\text{Si}_{1-y}\text{C}_y$ heterostructures for n-type MOS transistors** - J.-M. Hartmann, T. Ernst, V. Loup, F. Ducroquet, G. Rolland, P. Holliger, F. Laugier, D. Lafond, M.N. Séméria and S. Deleonibus (CEA-DRT – LETI/DTS – CEA/GRE.)
Short
- 16:36 - 16:40 **A new technique to fabricate Ultra-Shallow-Junctions, combining in-situ vapor HCl etching and in-situ doped epitaxial SiGe re-growth** - Roger Loo[1], Matty Caymax[1], Philippe Meunier-Beillard[2], Ivan Peytier[1], Stefan Kubicek[1], Peter Verheyen[1], Richard Lindsay[1], and Olivier Richard[1] ([1]IMEC, [2]Philips Research Leuven)
Short
- 16:40 - 16:44 **In-situ B doping of SiGe(C) using BCl_3 by hot-wall LPCVD** - Yasuo Kunii, Yasuhiro Inokuchi, Atsushi Moriya and Harushige Kurokawa, Junichi Murota* (Hitachi Kokusai Electric Inc., *Tohoku University)
Short
- 16:44 - 16:48 **Low-Temperature Dopant Activation Technology Using Elevated Ge-S/D Structure** - Hideki Takeuchi, Pushkar Ranade and Tsu-Jae King (University of California at Berkeley)
Short
- 16:48 - 16:52 **Relationship between Total Impurity(B or P) and Carrier Concentrations in SiGe Epitaxial Film Produced by the Thermal Treatment** - Jintae Noh, Shinobu Takehiro, Masao Sakuraba and Junichi Murota. (Tohoku University)
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- 16:52 - 16:56 **Characterization of As⁺-ion-implanted layers in strained-Si/SiGe/Si hetero-structures** - Short
T. Ishida*, T. Inada**, N. Sugii*** and S. Irieda* (*Hosei University, **Hosei University Reserch Institute, ***Hitachi Ltd.)
- 16:56 - 17:00 **Segregation of Boron to Polycrystalline and Single-crystal Si_{1-x-y}Ge_xC_y and Si_{1-y}C_y Layers** - E. J. Stewart and J. C. Sturm (Princeton University)
- 17:00 - 17:04 **High Resolution Depth Profiling of Dopants in SiGe on Si (001)** - N.L Rowell*, D.C. Short
Houghton**, M. Ward***, and D. Webb*** (*National Research Council of Canada, **AIXTRON Inc., ***ATMI Corp.)
- 17:04 - 17:08 **Thin, strain relaxed Si_{1-x}Ge_x buffer layers on Si(001) substrates with low defect density and surface roughness** - Late News
S.H. Christiansen, P.M. Mooney, J.O. Chu (IBM T.J. Watson Research Center)
- 17:08 - 17:25 **Break [Next : Poster Session (2)]**

[Parallel Session]

Session VIII-B : Process Tech., Quantum Dot and Optical Devices (Symposion : Room B)

- 13:20 - 13:35 **Reactive Ion Etching of Si_{1-x}Ge_x Alloy with Hydrogen Bromide** - Regular
C. S. Wang, D. Y. Shu, C. M. Liu, and M.-J. Tsai (ITRI)
- 13:35 - 13:50 **Etching Characteristics of Impurity-Doped Si_{1-x}Ge_x Epitaxial Films Using Electron-Cyclotron-Resonance Chlorine Plasma** - Regular
Hang-Sup Cho, Shinobu Takehiro, Masao Sakuraba and Junichi Murota. (Tohoku University)
- 13:50 - 14:05 **Ge dependent morphological change in poly-SiGe formed by Ni-mediated crystallization** - Regular
H. Kanno, I. Tsunoda, A. Kenjo, T. Sadoh, and M. Miyao (Kyushu University)
- 14:05 - 14:20 **Enhanced growth of amorphous interlayer in Ti thin films on strained Si/SiGe relaxed substrates** - Regular
H. C. Chen, S. W. Lee, S. L. Cheng, L. J. Chen, P. S. Chen* and C. W. Liu* (National Tsing Hua University, *ITRI)
- 14:20 - 14:35 **Selective epitaxial growth of Ge quantum dots on patterned Si(001) surfaces** - Regular
Lam. H. Nguyen*, V. Le Thanh, V. Yam, D. Débarre, M. Halbwx, D. Bouchier (Université Paris-Sud)
- 14:35 - 14:50 **Shape and composition change of Ge dots due to Si capping** - Regular
O. Kirfel[1], E. Müller[1], D. Grützmacher[1], K.Kern[2], A.Hesse[3], J. Stangl[3], V. Holý[3], G. Bauer[3] ([1]Paul Scherrer Institut, [2]École Polytechnique Fédérale de Lausanne, [3]University of Linz)
- 14:50 - 15:05 **Room Temperature 1.3 and 1.5 μm Electroluminescence from Si/Ge Quantum Dots (QDs)/Si Multi-layers** - Regular
Z.Pei, P.S.Chen, L.S.Lai, S.C. Lu, M.-J. Tsai, W. H. Chang*, W.Y. Chen*, A.T. Chou*, and T.M. Hsu* (ITRI, *National Central University)
- 15:05 - 15:20 **High Speed Lateral PIN Germanium-on-Silicon Photodetectors** - Regular
G. Dehlinger, J. D. Schaub, J. O. Chu, S. J. Koester, Q. C. Ouyang and A. Grill (IBM)
- 15:20 - 15:40 **Break**

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Session IX-B : Process Tech., Quantum Dot and Optical Devices (Symposium : Room B)

- 15:40 - 15:55 **SiGe PIN photodetector for infrared optical fiber links operating at 1.25 Gbit/s** - M. Regular
Jutzi[1], M. Berroth[1], G. Wöhl[2], C. Parry[2], E. Kasper[2] (Univ. Stuttgart)
- 15:55 - 15:59 **Enhanced crystal nucleation in a-SiGe/SiO₂ by ion-irradiation assisted annealing** - I. Short
Tsunoda, A. Kenjo, T. Sadoh, and M. Miyao (Kyushu University)
- 15:59 - 16:03 **Self-Organized Ge/Si Islands Grown by a Homemade UHV/CVD System** - Jinzhong Short
YU, Changjun HUANG, Buwen CHENG, Yuhua ZUO, Liping LUO, Zhenglin LEI and Qiming WANG (Institute of Semiconductors, Chinese Academy of Sciences)
- 16:03 - 16:07 **Kinetics of Ge quantum islands capping by silicon** - V. Yam, V. Le Thanh, D. Débarre Short
and D. Bouchier (Université Paris-Sud)
- 16:07 - 16:11 **Optical Properties of Stacked Ge/Si Quantum Dots with Different Spacer Thickness Grown by Chemical Vapor Deposition** - W. Y. Chen, W.-H. Chang, A. T. Chou, T. M. Short
Hsu, P. S. Chen*, Zingway Pei* and L. S. Lai* (National Central University, *ITRI)
- 16:11 - 16:15 **Novel composite Ge/Si/Ge quantum dots with high PL efficiency and improved Short
uniformity** - P. S. Chen, S. W. Lee, Y. H. Peng, Z. Pei, M. -J. Tsai, C. W. Liu (ITRI)
- 16:15 - 16:19 **Improved quality of Ge quantum dots in Ge/Si stacked layers by pre-intermixing Short
treatments** - S. W. Lee[1,2], P. S. Chen[2], Y. H. Peng[2], C. W. Liu[2] and L. J. Chen[1] ([1]National Tsing Hua University, [2]ITRI)
- 16:19 - 16:23 **Influence of Thermal Annealing on Compositional Mixing and Crystallinity of Highly- Short
Selective Grown Si Dots with Ge Core** - Yudi Darma, Hideki Murakami and Seiichi Miyazaki (Hiroshima University)
- 16:23 - 16:27 **Synthesis of Ge nanowires using Au nanoparticles catalyst on alumina template** - Ye Short
Zhizhen, Wu Guibin Huang Jingyun, CuiJiFeng, Zhao Binghui (Zhejiang University)
- 16:27 - 16:31 **2x2 Electrooptical Switch with SOI Waveguide** - Jinzhong YU, Qingfeng YAN, Jinsong Short
XIA, Zhongchao FAN, Zhangtao WANG, Shaowu CHEN (Institute of Semiconductors)
- 16:31 - 16:35 **Long-wavelength SiGe/Si MQW Resonant-Cavity-Enhanced photodetectors (RCE-PD) Short
for application in Optical Fiber Communication Network** - Qiming Wang, Cheng Li, Buwen Cheng, Qinqing Yang, Zhenglin Lei and Jinzhong Yu (Institute of Semiconductors)
- 16:35 - 16:39 **Fabrication of Epitaxial SiGe Optical Waveguide Structures** - Yihwan Kim, Dean Short
Berlin, and Arkadii Samoilov (Applied Materials Inc.)
- 16:39 - 16:43 **Schottky Quantum Dots Infrared Photodetector with Far Infrared Response** - Y. H. Short
Peng[1], Jen-Hsiang Lu[1], C. H. Kuan[1], C. W. Liu[1], Pang-Shiu Chen[2], Z. Pei[2], M.-J. Tsai[2], S. W. Lee[3], L. J. Chen[3], M. H. Ya[1], Y. F. Chen[1] ([1]National Taiwan University, [2]ITRI, [3]National Tsing Hua University)
- 16:43 - 16:47 **Coupling effect dependent on the thickness of the spacer layer between double layer of Ge quantum dots embedded in Si** - Yin Rao, Qi Gao, Zuimin Jiang and Fang Lu (Fudan Late News
University)
- 16:47 - 17:25 **Break [Next : Poster Session (2)]**

[End of Parallel Session]

- 17:25 - 19:00 **Session X : Poster Session (2)** (Symposium : Room C)
(see the page "xx")

Friday, January 17

Session XI : Invited Talks (4) (Symposion : Room A)

- 08:45 - 09:10 **SiGe-MMIC circuit techniques for 3G wireless terminals**
Invited - Noriharu Suematsu (Mitsubishi Electric Corp.)
- 09:10 - 09:35 **An Impedance Hopping Free 2GHz SiGe Step Gain Amplifier**
Invited - Mitsuru Tanabe (Matsushita Electric Industrial Co., Ltd.)
- 09:35 - 10:00 **DC- and RF-performance of a cost-effective SiGe technology**
Invited - V. Dudek, J. Berntgen, P. Maier, M. Tortschanoff, W. Kraus (ATMEL)
- 10:00 - 10:20 **Break**

[Parallel Session]

Session XII-A : New Technique (Symposion : Room A)

- 10:20 - 10:35 **Si Atomic Layer Epitaxy from Thermally Cracked Si₂H₆ (TCH-ALE) and the mechanisms of the adsorption process** - Yoshiyuki Suda and Kazushi Miki* (Tokyo University of Agriculture and Technology, *National Institute of Advanced Industrial Science and Technology)
- 10:35 - 10:50 **GeH₄ adsorption on Si(001) at room temperature: transfer of H atoms to Si sites and atomic exchange between Si and Ge** - Takeshi Murata, Maki Suemitsu (Tohoku University)
- 10:50 - 10:54 **Si self-diffusion in heavily B-doped epitaxial silicon** - K. Toyonaga[1], S. Rahamah Bt Aid[1], Y. Nakabayashi[1], S. Matsumoto[1], M. Sakuraba[2], Y. Shimada[2], A. Hashiba[2], and J. Murota[2] ([1]Keio University, [2]Tohoku University)
- 10:54 - 10:58 **Adsorption kinetics of dimethylsilane on Si(001)** - K.Senthil[1], H.Nakazawa[2] and M.Suemitsu[1] ([1]Tohoku University, [2]Hiroasaki University)
- 10:58 - 11:02 **Kinetics of Epitaxial Growth of Si and SiGe films on (110) Si Substrates** - N. Sugiyama, Y. Moriyama, S. Nakaharai, T. Tezuka, T. Mizuno and S. Takagi (MIRAI project, ASET)
- 11:02 - 11:06 **Local atomic structure in Czochralski-grown Ge_{1-x}Si_x bulk alloys** - I. Yonenaga, M. Sakurai, M. H. F. Sluiter and Y. Kawazoe (Tohoku University)
- 11:06 - 11:10 **Epitaxial Growth of N Delta Doped Si Films on Si(100) by Alternately Supplied NH₃ and SiH₄** - Youngcheon Jeong, Masao Sakuraba and Junichi Murota (Tohoku University)
- 11:10 - 11:30 **Break [Next : Poster Session (3)]**

[Parallel Session]

Session XII-B : Circuit Technology (Symposion : Room B)

- 10:20 - 10:35 **Static Frequency Divider Circuit using Strained SiGe p-MODFETs** - D. V. Singh, S. J. Koester, J. O. Chu, K. A. Jenkins, P. M. Mooney, Q. C. Ouyang, N. Ruiz, J. A. Ott, D. Ralston*, M. Wetzel*, P. M. Asbeck*, V. V. Patel, and A. Grill (IBM Research Division, *University of California)
- 10:35 - 10:50 **SiGe based Low Noise Amplifier for WLAN applications** - J.Sadowy[1, 2], V.Le-Goascoz[2], I.Telliez[2], J.Graffeuil[1], E.Tournier[1], L. Escotte[1] and R. Plana[1]. ([1]LAAS-CNRS, [2]STMICROELECTRONICS)

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- 10:50 - 10:54 **The Comparison of Isolation Technologies and Device Models on SiGe Bipolar Low Noise Amplifier** - W.-C. Hua[a], T.-Y. Yang[b], C. W. Liu[a,b] ([a]National Taiwan University, [b]STC/ITRI)
- 10:54 - 10:58 **Design of a 4.4-5 GHz LNA in 0.25- μ m SiGe BiCMOS Technology** - Paolo Crippa, Simone Orcioni, Francesco Ricciardi, and Claudio Turchetti (University of Ancona)
- 10:58 - 11:02 **Design of a DC-5 GHz MOS-based SPDT T/R Switch in 0.25- μ m SiGe BiCMOS Technology** - Paolo Crippa, Simone Orcioni, Francesco Ricciardi, and Claudio Turchetti (University of Ancona)
- 11:02 - 11:06 **A 2.9GHz-Band SiGe-MMIC On-Chip VCO** - Yasuhiro Nabeno, Masayoshi Ono, Takayuki Sugano, Masahiko Nakanishi, Noriharu Suematsu (Mitsubishi Electric Corp.)
- 11:06 - 11:30 **Break [Next : Poster Session (3)]**

[End of Parallel Session]

- 11:30 - 12:30 **Session XIII : Poster Session (3)** (Symposion : Room C)
(see the page "xxiv")
- 12:30 - 13:45 **Lunch**

Session XIV : Invited Talks (5) (Symposion : Room A)

- 13:45 - 14:10 **Low-cost Circuit Solutions for Micro- and Millimeter Wave Systems using Commercially Available SiGe Technologies**
- Hermann Schumacher, Peter Abele, Ertugrul Sönmez, Kai-Boris Schad, and Andreas Trasser (University of Ulm)
- 14:10 - 14:35 **Optimization of SiGe HBTs for Industrial Applications**
- V. Palankovski and S. Selberherr (Institute for Microelectronics, TU Vienna)
- 14:35 - 15:00 **Fabrication and Device Characteristics of Strained-Si-On-Insulataor (Strained-SOI) CMOS**
- Shin-ichi Takagi, Tomohisa Mizuno, Tsutomu Tezuka, Naoharu Sugiyama, Toshinori Numata, Koji Usuda, Yoshihiko Moriyama, Shu Nakaharai, Junji Koga, Akihito Tanabe and Tatsuro Maeda* (MIRAI-Project, ASET, *National Institute of Advanced Industrial Science and Technology (AIST))
- 15:00 - 15:15 **Closing Session** (Symposion : Room A)

Poster Session (1)

17:20 - 18:40 Wednesday, January 15

MOSFET

- P1-01 **25nm Gate Length Strained Silicon CMOS** - Qi Xiang, Jung-Suk Goo, Haihong Wang, Yayoi Takamura, Bin Yu, James Pan, Ammar Nayfeh, Allison Holbrook, Farzad Arasnia, Eric Paton, Paul Besser, Max Sidorov, Ercan Adem, Anthony Lochtefeld*, Glyn Braithwaite*, Matthew Currie*, Richard Hammond*, Mayank Bulsara*, Ming-Ren Lin (Advanced Micro Devices, Inc., *AmberWave Systems Corporation)
- P1-02 **Performance Enhancement in 70nm Channel Length Strained Si_{0.9}Ge_{0.1} pMOSFETs** - Zhonghai Shi, David Onsongo, Raghav Rai*, Srikanth B. Samavedam* and Sanjay K. Banerjee (The University of Texas at Austin, *Motorola (Digital DNA Laboratories, Dan Noble Center))
- P1-03 **Fabrication of 0.12- μ m SiGe-Channel MOSFET Containing High Ge Fraction with Ultrashallow Source/Drain Formed by Selective B-Doped SiGe CVD** - Doohwan Lee, Shinobu Takehiro, Masao Sakuraba, Junichi Murota and Toshiaki Tsuchiya* (Tohoku University, *Shimane University)
- P1-04 **Fabrication of strained Ge channel p-MOSFET with extremely high mobility** - T. Irisawa, S. Koh, K. Nakagawa*, Y. Shiraki (The University of Tokyo, *Yamanashi University)
- P1-05 **Strained-SiGe Channel p-MOSFETs with Platinum-Germanosilicide Schottky Source/Drain** - Keiji Ikeda, Yoshimi Yamashita, Akira Endoh, Tetsu Fukano, Kohki Hikosaka, and Takashi Mimura (Fujitsu Laboratories)
- P1-06 **SiGe Elevated Source/Drain Structure and Nickel Silicide Contact Layer for sub 0.1 μ m MOSFET** - JeoungChill Shim, HyuckJae Oh, Hoon Choi, Takeshi Sakaguchi, Hiroyuki Kurino and Mitsumasa Koyanagi (Tohoku University)
- P1-07 **Low frequency noise suppression and DC characteristics enhancement in sub- μ m metamorphic p-MOSFETs with strained Si_{0.3}Ge_{0.7} channel grown by MBE** - M. Myronov, S. Durov, O.A. Mironov, E.H.C. Parker and T.E. Whall, T. Hackbarth*, G. Hock*, H.J. Herzog* and U. Konig* (University of Warwick, *DaimlerChrysler Research Center)
- P1-08 **Low-Frequency Noise Characteristics in Strained SiGe Channel pMOSFET** - Akira Asai, Junko Sato-Iwanaga, Akira Inoue, Yoshihiro Hara, Yoshihiko Kanzawa, Haruyuki Sorada, Takahiro Kawashima, Teruhito Ohnishi, Takeshi Takagi, and Minoru Kubo (Matsushita Electric Industrial Co., Ltd.)
- P1-09 **High Performance Si/SiGe Heterostructure MOSFETs for Low power and Low Noise RF/Microwave Circuit Applications** - P. W. Li, W. M. Liao, C. C. Shih, T. S. Kuo, L. S. Lai*, Y. T. Tseng*, and M. J. Tsai* (National Central University, *ITRI)
- P1-10 **A Proposal of Multi-Layer Channel MOSFET: The Application of Selective Etching for Si/SiGe Stacked Layers** - T. Sakai, S. Ohmi, D. Sasaki, M. Sakuraba* and J. Murota* (Tokyo Institute of Technology, *Tohoku University)
- P1-11 **Low Frequency Noise and Hetero-Interface Traps in SiGe-Channel pMOSFETs** - Toshiaki Tsuchiya, Yuji Imada, and Junichi Murota* (Shimane University, *Tohoku University)
- P1-12 **Investigation of the Leakage Current in Si_{0.7}Ge_{0.3} pMOSFETs Fabricated by Selective Epitaxial Growth** - A. Inoue, H. Sorada, Y. Hara, K. Nozawa, A. Asai Y. Kanzawa and T. Takagi (Matsushita Electric Industrial Co., Ltd.)

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- P1-13 **Influence of roughness with long correlation length on the electron mobility of strained silicon devices** - Isao Kitagawa, Takuya Maruizumi, and Nobuyuki Sugii (Hitachi)
- P1-14 **Electrical properties of Si_{1-y}C_y/Si/SiO₂ stacks for sub 50nm strained-channel nMOSFETs** - [1,2]F. Ducroquet, [1]T. Ernst, [1,2]O. Weber, [1]J.-M. Hartmann, [1]V. Loup, [3]P. Besson, [1]L. Brévard, [1]J.L. Di Maria, [1]S. Deleonibus ([1]CEA – LETI/DTS – CEA/GRE, [2]LPM, INSA-Lyon, [3]STMICROELECTRONICS)
- P1-15 **Analysis of carrier generation lifetime in strained-Si / SiGe heterojunction MOSFETs from capacitance transient** - L.K.Bera, Shajan Mathew, N.Balasubramanian, G. Braithwaite*, M.T. Currie*, F. Singaporewala*, J. Yap*, R. Hammond*, A. Lochtefeld*, M. T. Bulsara*, and E. A. Fitzgerald* (Institute of Microelectronics, *AmberWave Systems Corp.)
- P1-16 **Minority Carrier Lifetime and Diffusion Length in Si_{1-x-y}Ge_xC_y and Si_{1-y}C_y Heterolayers** - S. K. Samanta, G. K. Dalapati, S. Chatterjee and C. K. Maiti (IIT)
- P1-17 **Electrical Properties of ZrO₂ Films on Si_{1-x-y}Ge_xC_y Epitaxial Layers** - S. Chatterjee, G. K. Dalapati, S. K. Samanta, and C. K. Maiti (IIT)
- P1-18 **Low-voltage CMOS operation of SiGe Heterostructure DT MOS** - H. Sorada, A. Inoue, Y. Hara, K. Nozawa, A. Asai, T. Kawashima, K. Katayama, and T. Takagi (Matsushita Electric Industrial Co., Ltd)
- P1-19 **Fabrication of 50 nm high performance strained-SiGe pMOSFETs with Selective Epitaxial Growth** - Roger Loo, Matty Caymax, Romain Delhougne, Nadine Collaert, Peter Verheyen** and Kristin De Meyer** (IMEC, **K.U. Leuven)

HBT

- P1-20 **Avalanche Considerations in SiGe HBT Scaling** - Greg Freeman, Basanth Jagannathan, Jae-Sung Rieh (IBM Microelectronics)
- P1-21 **Emitter Resistance Improvement in High-Performance SiGe HBTs** - Alvin Joseph, Peter Geiss, Xuefeng Liu, Jeffrey Johnson, Kathy Schonenberg*, Ashima Chakravarti*, David Ahlgren*, and James Dunn (IBM)
- P1-22 **Self-Aligned Heavily-Boron-Doped SEG SiGe HBT** - Eiji Ohue[1], Yukihiro Kiyota[1], Takashi Hashimoto[1], Tsutomu Udo[2], Akihiro Kodama[3], Hiromi Shimamoto[3], Reiko Hayami[1] and Katsuyoshi Washio[1] ([1]Hitachi Ltd., [2]Hitachi ULSI Systems Co. Ltd., [3]Hitachi Device Engineering Co. Ltd.)
- P1-23 **Influence of the Extrinsic Base on the Base Current Kink in SiGe BJTs** - Alexei Sadovnikov, Tracey Krakowski, and Monir El-Diwany (National Semiconductor Corp.)
- P1-24 **Design and optimization of a 200 GHz SiGe HBT collector profile by TCAD.** - Andreas D. Stricker, Jeffrey B. Johnson, Greg Freeman, and Jae-Sung Rieh (IBM Microelectronics Division)
- P1-25 **The Effect of C on Emitter-Base Design for a Single-Polysilicon SiGe:C HBT with an IDP Emitter** - Erik Haralson, Erdal Suvar, Gunnar Malm, Henry Radamson, Yong-Bin Wang, Mikael Östling (Royal Institute of Technology (KTH))
- P1-26 **Characterization of leakage current for SiGeC heterojunction bipolar transistors with a selectively grown collector** - E. Suvar, E. Haralson, H. H. Radamson, Y.-B. Wang, B. G. Malm and M. Östling (Royal Institute of Technology (KTH))

- P1-27 **ESD Characterization of SiGe HBT in 0.18- μm SiGe BiCMOS Process** - Shiao-Shien Chen, Tung-Yang Chen, Tien-Hao Tang, Shao-Chang Huang, Tsun-Lai Hsu, Hua-Chou Tseng, Jen-Kon Chen, and Chiu-Hsiang Chou* (United Microelectronics Corporation, *Providence University)
- P1-28 **The optimal base design for SiGe heterojunction bipolar transistors with high f_T** - L.S. Lai, Y.H. Liu, C.S. Liang, Y.T. Tseng, Y.M. Shiu, P.S. Chen, S.C. Lu, C.W. Liu and M.-J. Tsai (ITRI)
- P1-29 **Low frequency noise behavior of advanced SiGe HBT** - A.Rennane*, L.Bary*, G. Niu**, J.D. Cressler**, J. Joseph***, J.Graffeuil* and R. Plana* (*LAAS-CNRS, **Alabama Microelectronics Science and Technology Center, ***IBM Microelectronics)
- P1-30 **Reliability properties of SiGe HBT** - A.Rennane*, L.Bary*, J.L.Roux **, J.Kuchenbecker **, J.Graffeuil* and R. Plana* (*LAAS-CNRS and Université Paul Sabatier, ** CNES)
- P1-31 **Achieving a SiGe HBT Epitaxial Emitter with Novel Low Thermal Budget Technique** - Paul Brabant, Jianqing Wen, Joe Italiano, Trevan Landin, Nyles Cody and Lee Haen (ASM America Inc.)
- P1-32 **Evaluation of Compact Noise Modeling for Si/SiGe HBTs Based on Hierarchical Hydrodynamic Noise Simulation** - M. Bartels , B. Neinhüs , C. Jungemann , B. Meinerzhagen (Universität Bremen)
- P1-33 **Comparison of State-of-the-Art Bipolar Compact Models for SiGe-HBTs** - A. Chakravorty, R. Garg, and C. K. Maiti (IIT)
- P1-34 **A noise and power analysis of SiGe HBT's for RF applications** - J. Raoult*, J. Verdier*, F. Calmon*, P.J. Viverge**, C. Gontrand* (*Laboratoire de Physique de la Matière, **Centre de Génie Electrique de Lyon)
- P1-35 **A Direct Extraction Feature for Scattering Parameters of SiGe-HBTs** - S. Wagner[1], V. Palankovski[1], T. Grasser[1], G. Röhrer[2], and S. Selberherr[1] ([1]TU Vienna, [2]AustriamicrosystemsAG)
- P1-36 **Rigorous Modeling Approach to Numerical Simulation of SiGe-HBTs** - V. Palankovski[1], G. Röhrer[2], T. Grasser[1], S. Smirnov[1], H. Kosina[1], and S. Selberherr[1] ([1]TU Vienna, [2]AustriamicrosystemsAG)

The Other Devices

- P1-37 **Resonant tunneling in Si-SiGe superlattices on relaxed buffer substrates** - S. Tsujino, S. Mentese, L. Diehl, E. Muller, B. Haas, D. Bachli, S. Stutz, H. Sigg, D. Grutzmacher, J. Faist* (Paul Scherrer Institut, *University of Neuchatel)
- P1-38 **60nm gate-length Si/SiGe HEMT** - A. Kasamatsu*, K. Kasai*, K. Hikosaka*, T. Matsui* and T. Mimura** (*Communications Research Laboratory, **Fujitsu Laboratories Ltd.)
- P1-39 **SiGe virtual substrate HMOS transistor for analogue applications** - K. Michelakis, S. Despotopoulos, V. Gaspari, A. Vilches, K. Fobelets, C. Papavassiliou, C. Toumazou, J. Zhang (Imperial College)
- P1-40 **Effect of temperature on the transfer characteristic of a 0.5 μm -gate Si:SiGe depletion-mode n-MODFET** - V. Gaspari†, K. Fobelets, J.E. Velazquez-Perez*, R. Ferguson, K. Michelakis, S. Despotopoulos, and C. Papavassiliou (Imperial College London, *Universidad de Salamanca)

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- P1-41 **Influence of substrate thinning on the threshold voltage of Si:SiGe Heterojunction MOSFETs** - S.M. Li, K. Fobelets, J.E. Velazquez-Perez*, V. Gaspari, R. Ferguson, K. Michelakis, S. Despotopoulos, and C. Papavassiliou (Imperial College London, *Universidad de Salamanca)
- P1-42 **Nonvolatile Memory based on Ge/Si Hetero-Nanocrystals** - H.G. Yang, Y. Shi, L. Pu, R. Zhang, B. Shen, P. Han, S.L. Gu, and Y.D. Zheng (Nanjing University)
- P1-43 **Si/SiGe heterojunction collector for low loss operation of Trench IGBT** - Tsugutomo Kudoh and Tanemasa Asano (Kyushu Institute of Technology)
- P1-44 **Hole-tunneling nanoscale Si_{0.6}Ge_{0.4}/Si diode** - Ping Han*, Masao Sakuraba, Junichi Murota, and Youdou Zheng* (* Nanjing University, Tohoku University)

Poster Session (2)

17:25 - 19:00 Thursday, January 16

Strain Control , Epitaxy and Impurity

- P2-01 **Development of a new type of SiGe thin strain relaxed buffer based on the incorporation of a carbon-containing layer** - Romain Delhougne, Philippe Meunier-Beillard*, Matty Caymax, Roger Loo, Wilfried Vandervorst (IMEC, *Philips Research Leuven)
- P2-02 **Thin strain relaxed SiGe buffer layers on Si and SOI wafers made by He⁺ ion implantation and annealing** - S. Mantl[1], B. Holländer[1], N. Hüging[2], M. Luysberg[2], St. Lenk[1], S.M. Hoog[1], H.-J. Herzog[3], T. Hackbarth[3], R. Loo[4], M. Bauer[5] ([1-2]Research Centre Juelich, [3]DaimlerChrysler, [4]IMEC, [5]ASM Germany)
- P2-03 **Fabrication SiGe-on-insulator by rapid thermal annealing of Ge thin film on Si-on-insulator substrate** - K.Kutsukake, N.Usami, K.Fujiwara, T.Ujihara, G.Sazaki, B.P.Zhang *and K.Nakajima (Tohoku University, *The Institute of Physical and Chemical Research (RIKEN))
- P2-04 **Formation of thin SiGe virtual substrates by ion implantation into Si substrates** - K. Sawano^a, Y. Hirose^b, S. Koh^a, K. Nakagawa^c, T. Hattori^b, and Y. Shiraki^a ((a) The University of Tokyo, (b) Musashi Institute of Technology, (c) Yamanashi University)
- P2-05 **Strain-relaxation mechanisms of SiGe layers formed by two-step growth on Si(001) substrates** - T. Egawa, T. Yamamoto, N. Taoka, O. Nakatsuka, A. Sakai, S. Zaima, and Y. Yasuda (Nagoya University)
- P2-06 **Dislocation structures and strain-relaxation in SiGe buffer layers on Si (001) with thin Ge interlayer** - T. Yamamoto, T. Egawa, N. Taoka O. Nakatsuka, A. Sakai, S. Zaima and Y. Yasuda (Nagoya University)
- P2-07 **Evaluation of relaxation of strained-Si layers on SiGe-On-Insulator (SGOI) structures after mesa isolation** - Koji Usuda, T.Mizuno, T.Tezuka, N.Sugiyama, Y.Moriyama, S.Nakaharai and S.Takagi (MIRAI Project, ASET)
- P2-08 **Influence of SiGe interlayer on the initial growth of Si_{1-x-y}Ge_xC_y on Si(100)** - S. Ariyoshi, S. Takeuchi, O. Nakatsuka,* A. Sakai, S. Zaima,** and Y. Yasuda (Nagoya University)
- P2-09 **Roughening mechanisms of tensily strained Si_{1-x-y}Ge_xC_y films grown by UHV-CVD : a way to maximize substitutional C incorporation** - Cyril Calmes[1], Daniel Bouchier[1], Catherine Clerc[2], Yulin Zheng[3] ([1-2]Université Paris-Sud, [3]Université Paris VI et Paris VII)
- P2-10 **Thin, strain relaxed Si_{1-x}Ge_x buffer layers on Si(001) substrates with low defect density and surface roughness** - S.H. Christiansen, P.M. Mooney, J.O. Chu (IBM T.J. Watson Research Center)

Epitaxy

- P2-11 **Low temperature H₂ cleaning of Si surface for 0.18-um SiGe-BiCMOS base epitaxy** - T.Tominari, Y.Nonaka, K.Sakai, S.Wada, T.Saito, K.Tokunaga, T.Jimbo, T.Udo*, Y.Kiyota and T.Hashimoto (Hitachi,Ltd., *Hitachi ULSI Systems)

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- P2-12 **N₂ as carrier gas: an alternative to H₂ for enhanced epitaxy of Si, SiGe and SiGe:C** - P. Meunier-Beillard*, M. Caymax**, K. Van Nieuwenhuysen**, G. Doumen**, B. Brijs**, M. Hopstaken†, L. Geenen** and W. Vandervorst** (*Philips Research Leuven, **IMEC, †Philips Research Laboratories)
- P2-13 **Selective Epitaxial Growth of Si and SiGe for MOS transistors** - J.-M. Hartmann, F. Bertin, G. Rolland, F. Laugier, M.N. Séméria, P. Besson and P. Gentile (CEA-DRT – LETI/DTS – CEA/GRE.)
- P2-14 **Production-ready Dry Cleaning and Deposition Processes for Low-Temperature Si and SiGe Epitaxy** - Kummer, M. [a], Dommann, A.[a], Buschbaum T. [b], Buschbeck, H. M.[b], Erhart, A.[b], Goeggel, Y.[b], Rosenblad, C. [b], Wiltsche, S.[b], Ramm, J.[b] ((a) Interstate University of Applied Science, (b) Unaxis Semiconductors)
- P2-15 **Si_{1-x}Ge_x/Si strained epitaxial layer grown by UV/UHV/CVD** - Huiyong Hu, Heming Zhang, Xianying Dai, *Kaicheng Li, Bin Shu, Yi Lv (Xidian University, *National Lab of Analog Ics)
- P2-16 **Si/SiGe Selective Epitaxial Growth by a Single-wafer Cold-wall UHVCVD System** - Supika Mashiro, Hiroki Date, Junko Nakatsuru, Satoshi Hitomi, and Junro Sakai (Anelva Corporation)
- P2-17 **Carbon incorporation study for SiGeC epitaxy optimization in RTCVD** - F. Deleglise, C. Fellous and D. Dutartre (STMICROELECTRONICS)
- P2-18 **Low Temperature, High Growth Rate Epitaxial Silicon and Silicon Germanium Alloy Films** - Michael A. Todd and K. Doran Weeks (ASM America)
- P2-19 **Growth of high quality epitaxial Si_{1-x-y}Ge_xC_y layers using chemical vapor deposition** - J. Hallstedt, E. Suvar, P. O. A. Persson*, L.Hultman* and H. H. Radamson (Royal Institute of Technology (KTH), *Linköpings Universitet)
- P2-20 **Reduced Pressure Chemical Vapour Deposition of high C content Si / Si_{1-y}C_y heterostructures for n-type MOS transistors** - J.-M. Hartmann, T. Ernst, V. Loup, F. Ducroquet, G. Rolland, P. Holliger, F. Laugier, D. Lafond, M.N. Séméria and S. Deleonibus (CEA-DRT – LETI/DTS – CEA/GRE.)
- P2-21 **Reduced Pressure Chemical Vapour Deposition of Si / SiGeC heterostructures using a chlorinated chemistry** - V. Loup, J.-M. Hartmann, G. Rolland, P. Holliger, F. Laugier, D. Lafond and M.N. Séméria (CEA-DRT – LETI/DTS – CEA/GRE.)
- P2-22 **Characterization of Ge Gradients in SiGe HBT Test Structures by AES Depth Profile Simulation** - D. Krüger, A. Penkov*, Y. Yamamoto, A. Goryachko**, and B. Tillack (IHP, *National Technical University, **Brandenburg Technical University)

Impurity

- P2-23 **High Performance SiGe:C HBTs Using Atomic Layer Base Doping** - Bernd Tillack, Yuji Yamamoto, Dieter Knoll, Bernd Heinemann, Peter Schley, Biswanath Senapati and Dietmar Krüger (IHP)
- P2-24 **Enhanced intrinsic Arsenic diffusion in SiGe strained layers.** - A. Pakfar, P. Holliger*, C. Fellous, D. Dutartre. T. Schwartzmann and H. Jaouen. (STMICROELECTRONICS, *CEA-Leti)
- P2-25 **On the mechanism of ion- implanted As diffusion in relaxed SiGe** - S. Eguchi, S. J. Rhee[1], D.L. Kwong[1], I. Åberg[2], and J.L. Hoyt [2] (Hitachi Ltd., [1]Univ. of Texas at Austin, [2]MIT)

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- P2-26 **A new technique to fabricate Ultra-Shallow-Junctions, combining in-situ vapor HCl etching and in-situ doped epitaxial SiGe re-growth** - Roger Loo[1], Matty Caymax[1], Philippe Meunier-Beillard[2], Ivan Peytier[1], Stefan Kubicek[1], Peter Verheyen[1], Richard Lindsay[1], and Olivier Richard[1] ([1]IMEC, [2]Philips Research Leuven)
- P2-27 **In-situ B doping of SiGe(C) using BCl₃ by hot-wall LPCVD** - Yasuo Kunii, Yasuhiro Inokuchi, Atsushi Moriya and Harushige Kurokawa, Junichi Murota* (Hitachi Kokusai Electric Inc., *Tohoku University)
- P2-28 **Low-Temperature Dopant Activation Technology Using Elevated Ge-S/D Structure** - Hideki Takeuchi, Pushkar Ranade and Tsu-Jae King (University of California at Berkeley)
- P2-29 **Relationship between Total Impurity(B or P) and Carrier Concentrations in SiGe Epitaxial Film Produced by the Thermal Treatment** - Jintae Noh, Shinobu Takehiro, Masao Sakuraba and Junichi Murota. (Tohoku University)
- P2-30 **Characterization of As⁺-ion-implanted layers in strained-Si/SiGe/Si hetero-structures** - T. Ishida*, T. Inada**, N. Sugii*** and S. Irieda* (*Hosei University, **Hosei University Reserch Institute, ***Hitachi Ltd.)
- P2-31 **Segregation of Boron to Polycrystalline and Single-crystal Si_{1-x-y}Ge_xC_y and Si_{1-y}C_y Layers** - E. J. Stewart and J. C. Sturm (Princeton University)
- P2-32 **High Resolution Depth Profiling of Dopants in SiGe on Si (001)** - N.L Rowell*, D.C. Houghton**, M. Ward***, and D. Webb*** (*National Research Council of Canada, **AIXTRON Inc., ***ATMI Corp.)

Process Tech.

- P2-33 **Reactive Ion Etching of Si_{1-x}Ge_x Alloy with Hydrogen Bromide** - C. S. Wang, D. Y. Shu, C. M. Liu, and M.-J. Tsai (ITRI)
- P2-34 **Etching Characteristics of Impurity-Doped Si_{1-x}Ge_x Epitaxial Films Using Electron-Cyclotron-Resonance Chlorine Plasma** - Hang-Sup Cho, Shinobu Takehiro, Masao Sakuraba and Junichi Murota. (Tohoku University)
- P2-35 **Ge dependent morphological change in poly-SiGe formed by Ni-mediated crystallization** - H. Kanno, I. Tsunoda, A. Kenjo, T. Sadoh, and M. Miyao (Kyushu University)
- P2-36 **Enhanced growth of amorphous interlayer in Ti thin films on strained Si/SiGe relaxed substrates** - H. C. Chen, S. W. Lee, S. L. Cheng, L. J. Chen, P. S. Chen* and C. W. Liu* (National Tsing Hua University, *ITRI)
- P2-37 **Enhanced crystal nucleation in a-SiGe/SiO₂ by ion-irradiation assisted annealing** - I. Tsunoda, A. Kenjo, T. Sadoh, and M. Miyao (Kyushu University)

Quantum Dot

- P2-38 **Selective epitaxial growth of Ge quantum dots on patterned Si(001) surfaces** - Lam. H. Nguyen*, V. Le Thanh, V. Yam, D. Débarre, M. Halbwax, D. Bouchier (Université Paris-Sud)
- P2-39 **Shape and composition change of Ge dots due to Si capping** - O. Kirfel[1], E. Müller[1], D. Grützmacher[1], K. Kern[2], A. Hesse[3], J. Stangl[3], V. Holý[3], G. Bauer[3] ([1]Paul Scherrer Institut, [2]École Polytechnique Fédérale de Lausanne, [3]University of Linz)

Poster - Thu., Jan. 16

- P2-40 **Self-Organized Ge/Si Islands Grown by a Homemade UHV/CVD System** - Jinzhong YU, Changjun HUANG, Buwen CHENG, Yuhua ZUO, Liping LUO, Zhenglin LEI and Qiming WANG (Institute of Semiconductors, Chinese Academy of Sciences)
- P2-41 **Kinetics of Ge quantum islands capping by silicon** - V. Yam, V. Le Thanh, D. Débarre and D. Bouchier (Université Paris-Sud)
- P2-42 **Optical Properties of Stacked Ge/Si Quantum Dots with Different Spacer Thickness Grown by Chemical Vapor Deposition** - W. Y. Chen, W.-H. Chang, A. T. Chou, T. M. Hsu, P. S. Chen*, Zingway Pei* and L. S. Lai* (National Central University, *ITRI)
- P2-43 **Novel composite Ge/Si/Ge quantum dots with high PL efficiency and improved uniformity** - P. S. Chen, S. W. Lee, Y. H. Peng, Z. Pei, M. -J. Tsai, C. W. Liu (ITRI)
- P2-44 **Improved quality of Ge quantum dots in Ge/Si stacked layers by pre-intermixing treatments** - S. W. Lee[1,2], P. S. Chen[2], Y. H. Peng[2], C. W. Liu[2] and L. J. Chen[1] ([1]National Tsing Hua University, [2]ITRI)
- P2-45 **Influence of Thermal Annealing on Compositional Mixing and Crystallinity of Highly-Selective Grown Si Dots with Ge Core** - Yudi Darma, Hideki Murakami and Seiichi Miyazaki (Hiroshima University)
- P2-46 **Synthesis of Ge nanowires using Au nanoparticles catalyst on alumina template** - Ye Zhizhen, Wu Guibin Huang Jingyun, CuiJiFeng, Zhao Binghui (Zhejiang University)
- P2-47 **Coupling effect dependent on the thickness of the spacer layer between double layer of Ge quantum dots embedded in Si** - Yin Rao, Qi Gao, Zuimin Jiang and Fang Lu (Fudan University)
- P2-48 **Reduced Pressure Chemical Vapour Deposition of Ge quantum dots** - J.-M. Hartmann, F. Bertin, G. Rolland and M.N. Séméria (CEA/GRE - LETI/DTS/STME/L2TI)

Optical Devices

- P2-49 **Room Temperature 1.3 and 1.5 μm Electroluminescence from Si/Ge Quantum Dots (QDs)/Si Multi-layers** - Z.Pei, P.S.Chen, L.S.Lai, S.C. Lu, M.-J. Tsai, W. H. Chang*, W.Y. Chen*, A.T. Chou*, and T.M. Hsu* (ITRI, *National Central University)
- P2-50 **High Speed Lateral PIN Germanium-on-Silicon Photodetectors** - G. Dehlinger, J. D. Schaub, J. O. Chu, S. J. Koester, Q. C. Ouyang and A. Grill (IBM)
- P2-51 **SiGe PIN photodetector for infrared optical fiber links operating at 1.25 Gbit/s** - M. Jutzi[1], M. Berroth[1], G. Wöhl[2], C. Parry[2], E. Kasper[2] (Univ. Stuttgart)
- P2-52 **2x2 Electrooptical Switch with SOI Waveguide** - Jinzhong YU, Qingfeng YAN, Jinsong XIA, Zhongchao FAN, Zhangtao WANG, Shaowu CHEN (Institute of Semiconductors)
- P2-53 **Long-wavelength SiGe/Si MQW Resonant-Cavity-Enhanced photodetectors (RCE-PD) for application in Optical Fiber Communication Network** - Qiming Wang, Cheng Li, Buwen Cheng, Qinqing Yang, Zhenglin Lei and Jinzhong Yu (Institute of Semiconductors)
- P2-54 **Fabrication of Epitaxial SiGe Optical Waveguide Structures** - Yihwan Kim, Dean Berlin, and Arkadii Samoilov (Applied Materials Inc.)
- P2-55 **Schottky Quantum Dots Infrared Photodetector with Far Infrared Response** - Y. H. Peng[1], Jen-Hsiang Lu[1], C. H. Kuan[1], C. W. Liu[1], Pang-Shiu Chen[2], Z. Pei[2], M.-J. Tsai[2], S. W. Lee[3], L. J. Chen[3], M. H. Ya[1], Y. F. Chen[1] ([1]National Taiwan University, [2]ITRI, [3]National Tsing Hua University)

Poster Session (3)

17:20 - 18:40 Friday, January 17

New Technique

- P3-01 **Si Atomic Layer Epitaxy from Thermally Cracked Si₂H₆ (TCH-ALE) and the mechanisms of the adsorption process** - Yoshiyuki Suda and Kazushi Miki* (Tokyo University of Agriculture and Technology, *National Institute of Advanced Industrial Science and Technology)
- P3-02 **GeH₄ adsorption on Si(001) at room temperature: transfer of H atoms to Si sites and atomic exchange between Si and Ge** - Takeshi Murata, Maki Suemitsu (Tohoku University)
- P3-03 **Si self-diffusion in heavily B-doped epitaxial silicon** - K. Toyonaga[1], S. Rahamah Bt Aid[1], Y. Nakabayashi[1], S. Matsumoto[1], M. Sakuraba[2], Y. Shimada[2], A. Hashiba[2], and J. Murota[2] ([1]Keio University, [2]Tohoku University)
- P3-04 **Adsorption kinetics of dimethylsilane on Si(001)** - K.Senthil[1], H.Nakazawa[2] and M.Suemitsu[1] ([1]Tohoku University, [2]Hiroasaki University)
- P3-05 **Kinetics of Epitaxial Growth of Si and SiGe films on (110) Si Substrates** - N. Sugiyama, Y. Moriyama, S. Nakaharai, T. Tezuka, T. Mizuno and S. Takagi (MIRAI project, ASET)
- P3-06 **Local atomic structure in Czochralski-grown Ge_{1-x}Si_x bulk alloys** - I. Yonenaga, M. Sakurai, M. H. F. Sluiter and Y. Kawazoe (Tohoku University)
- P3-07 **Epitaxial Growth of N Delta Doped Si Films on Si(100) by Alternately Supplied NH₃ and SiH₄** - Youngcheon Jeong, Masao Sakuraba and Junichi Murota (Tohoku University)
- P3-08 **Gas Control Technologies for SiGe deposition processes** - Nobuyasu Tomita, Hiroyuki Ono, Takuya Ikeda, Yoshiaki Sugimori and Satoshi Hasaka (Nippon Sanso Co.)
- P3-09 **Formation of Heavily P Doped Si Epitaxial Film on Si(100) by Multiple Atomic-Layer Doping Technique** - Yosuke Shimamune, Masao Sakuraba and Junichi Murota* (Tohoku University)
- P3-10 **Carbon Effect on Thermal Stability of Si Atomic Layer on Ge(100)** - Masaki Fujiu, Kazuya Takahashi, Masao Sakuraba and Junichi Murota* (Tohoku University)
- P3-11 **Ar Plasma Irradiation Effects in Atomically Controlled Si Epitaxial Growth** - Daisuke Muto, Masao Sakuraba*, Takuya Seino and Junichi Murota (Tohoku University)

Circuit Technology

- P3-12 **Static Frequency Divider Circuit using Strained SiGe p-MODFETs** - D. V. Singh, S. J. Koester, J. O. Chu, K. A. Jenkins, P. M. Mooney, Q. C. Ouyang, N. Ruiz, J. A. Ott, D. Ralston*, M. Wetzel*, P. M. Asbeck*, V. V. Patel, and A. Grill (IBM Research Division, *University of California)
- P3-13 **SiGe based Low Noise Amplifier for WLAN applications** - J.Sadowy[1, 2], V.Le-Goascoz[2], I.Telliez[2], J.Graffeuil[1], E.Tournier[1], L. Escotte[1] and R. Plana[1]. ([1]LAAS-CNRS, [2]STMICROELECTRONICS)
- P3-14 **The Comparison of Isolation Technologies and Device Models on SiGe Bipolar Low Noise Amplifier** - W.-C. Hua[a], T.-Y. Yang[b], C. W. Liu[a,b] ([a]National Taiwan University, [b]STC/ITRI)

Poster - Fri., Jan. 17

- P3-15 **Design of a 4.4-5 GHz LNA in 0.25- μ m SiGe BiCMOS Technology** - Paolo Crippa, Simone Orcioni, Francesco Ricciardi, and Claudio Turchetti (University of Ancona)
- P3-16 **Design of a DC-5 GHz MOS-based SPDT T/R Switch in 0.25- μ m SiGe BiCMOS Technology** - Paolo Crippa, Simone Orcioni, Francesco Ricciardi, and Claudio Turchetti (University of Ancona)
- P3-17 **A 2.9GHz-Band SiGe-MMIC On-Chip VCO** - Yasuhiro Nabeno, Masayoshi Ono, Takayuki Sugano, Masahiko Nakanishi, Noriharu Suematsu (Mitsubishi Electric Corp.)